



IPC-2222A

Sectional Design Standard for Rigid Organic Printed Boards

Developed by the IPC-2221/2222 Task Group (D-31B) of the Rigid
Printed Board Committee (D-30) of IPC

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Users of this publication are encouraged to participate in the
development of future revisions.

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Sectional Design Standard for Rigid Organic Printed Boards

1 SCOPE

This standard establishes the specific requirements for the design of rigid organic printed boards.

1.1 Purpose The requirements contained herein are intended to establish specific design details that **shall** be used in conjunction with IPC-2221 to produce designs intended to mount and attach components. The components may be through-hole, surface mount, fine pitch, ultra-fine pitch, array mounting or unpackaged bare die.

The organic materials may be homogeneous, reinforced, or used in combination with inorganic materials; the interconnections may be single, double, or multilayered. They may be any combination able to perform the physical, thermal, environmental, and electronic function.

1.2 Document Hierarchy Document hierarchy **shall** be in accordance with the generic standard IPC-2221.

1.3 Presentation Presentation **shall** be in accordance with the generic standard IPC-2221.

1.4 Interpretation Interpretation **shall** be in accordance with the generic standard IPC-2221.

1.5 Definition of Terms The definition of all terms used herein **shall** be in accordance with IPC-T-50 and as defined in 1.5.1.

1.5.1 As Agreed Between User and Supplier (AABUS) Indicates additional or alternate requirements to be decided between the user and the supplier in the procurement documentation. Examples include contractual requirements, modifications to purchase documentation and information on the drawing. Agreements can be used to define test methods, conditions, frequencies, categories or acceptance criteria within a test, if not already established.

1.6 Classification of Products Classification of products **shall** be in accordance with the generic standard IPC-2221 and as defined in 1.6.1.

1.6.1 Printed Board Type This standard provides design information for different printed board types. Printed board types are classified as:

Type 1 – Single-Sided Printed Board

Type 2 – Double-Sided Printed Board

Type 3 – Multilayer Printed Board without blind or buried vias

Type 4 – Multilayer Printed Board with blind and/or buried vias

Type 5 – Multilayer Metal Core Printed Board without blind or buried vias

Type 6 – Multilayer Metal Core Printed Board with blind and/or buried vias

1.7 Applicability The contents of this standard may not apply to certain leading edge technologies. Refer to IPC-2221 for additional information.

1.8 Revision Level Changes Changes that were incorporated in the current revision of this specification are indicated throughout by gray shading of the relevant subsection(s). Changes to a figure or table are indicated by gray shading of the Figure or Table header.